



501.43630X00

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant(s): N. KAWANABE, et al

Serial No.: 10/807,249

Filed: March 24, 2004

For: A METHOD OF MANUFACTURING A SEMICONDUCTOR DEVICE TO PROVIDE IMPROVED ADHESION BETWEEN BONDING AND BALL PORTIONS OF ELECTRICAL CONNECTORS (as amended)

Group:

**PRELIMINARY AMENDMENT**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

May 5, 2004

Sir:

The following preliminary amendments and remarks are respectfully submitted in connection with the above-identified application, as listed below and as set forth on the following pages:

Substitute Specification and Marked Up Version of Original Specification;

Amendment of the Abstract; and

Remarks are included following the amendments.